# **MOSFET** – N-Channel, SUPERFET II, FRFET

600 V, 76 A, 41 m $\Omega$ 

# FCH041N60F

#### Description

SUPERFET<sup>®</sup> II MOSFET is ON Semiconductor's brand-new high voltage super-junction (SJ) MOSFET family that is utilizing charge balance technology for outstanding low on-resistance and lower gate charge performance. This technology is tailored to minimize conduction loss, provide superior switching performance, dv/dt rate and higher avalanche energy. Consequently, SUPERFET II MOSFET is very suitable for the switching power applications such as PFC, server/telecom power, FPD TV power, ATX power and industrial power applications. SUPERFET II FRFET<sup>®</sup> MOSFET's optimized body diode reverse recovery performance can remove additional component and improve system reliability.

#### Features

- $650 \text{ V} @ \text{T}_{\text{J}} = 150^{\circ}\text{C}$
- Typ.  $R_{DS(on)} = 36 \text{ m}\Omega$
- Ultra Low Gate Charge (Typ. Q<sub>g</sub> = 277 nC)
- Low Effective Output Capacitance (Typ. Coss(eff.) = 748 pF)
- 100% Avalanche Tested
- This Device is Pb-Free and is RoHS Compliant

#### Applications

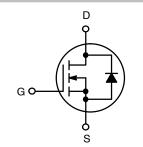
- Telecom / Server Power Supplies
- Industrial Power Supplies
- EV Charger
- UPS / Solar



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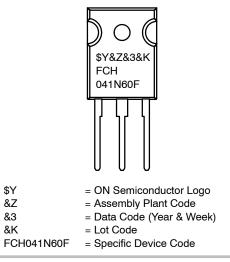
V <sub>DSS</sub>	R <sub>DS(ON)</sub> MAX	I <sub>D</sub> MAX		
600 V	41 m $\Omega$	76 A		



N-Channel MOSFET



#### MARKING DIAGRAM



#### **ORDERING INFORMATION**

See detailed ordering and shipping information on page 2 of this data sheet.

Symbol	Parameter	Value	Unit	
V <sub>DSS</sub>	Drain to Source Voltage	600	V	
V <sub>GSS</sub>	Gate to Source Voltage	DC	±20	V
		AC (f > 1 Hz)	±30	
I <sub>D</sub>	Drain Current	Continuous (T <sub>C</sub> = 25°C)	76	А
		Continuous (T <sub>C</sub> = 100°C)	48.1	
I <sub>DM</sub>	Drain Current	Pulsed (Note 1)	228	А
E <sub>AS</sub>	AS Single Pulsed Avalanche Energy (Note 2)		2025	mJ
I <sub>AR</sub>	Avalanche Current (Note 1)	15	А	
E <sub>AR</sub>	Repetitive Avalanche Energy (Note 1)		5.95	mJ
dv/dt	MOSFET dv/dt Peak Diode Recovery dv/dt (Note 3)		100	V/ns
			50	
PD	Power Dissipation	(T <sub>C</sub> = 25°C)	595	W
		Derate Above 25°C	4.76	W/°C
T <sub>J</sub> , T <sub>STG</sub> Operating and Storage Temperature Rang			-55 to +150	°C
ΤL	Maximum Lead Temperature for Soldering, 1/8" from Case for 5 s		300	°C

#### ABSOLUTE MAXIMUM RATINGS (T<sub>C</sub> = 25°C, Unless otherwise specified)

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected. 1. Repetitive rating: pulse-width limited by maximum junction temperature. 2.  $I_{AS} = 15 \text{ A}, \text{ R}_{G} = 25 \Omega$ , starting  $T_{J} = 25^{\circ}\text{C}$ . 3.  $I_{SD} \leq 38 \text{ A}, \text{ di/dt} \leq 200 \text{ A/}\mu\text{s}, \text{ V}_{DD} \leq 380 \text{ V}$ , starting  $T_{J} = 25^{\circ}\text{C}$ .

#### **THERMAL CHARACTERISTICS**

Symbol	Parameter	Value	Unit
$R_{ ext{ heta}JC}$	Thermal Resistance, Junction to Case, Max.	0.21	°C/W
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient, Max.	40	

#### PACKAGE MARKING AND ORDERING INFORMATION

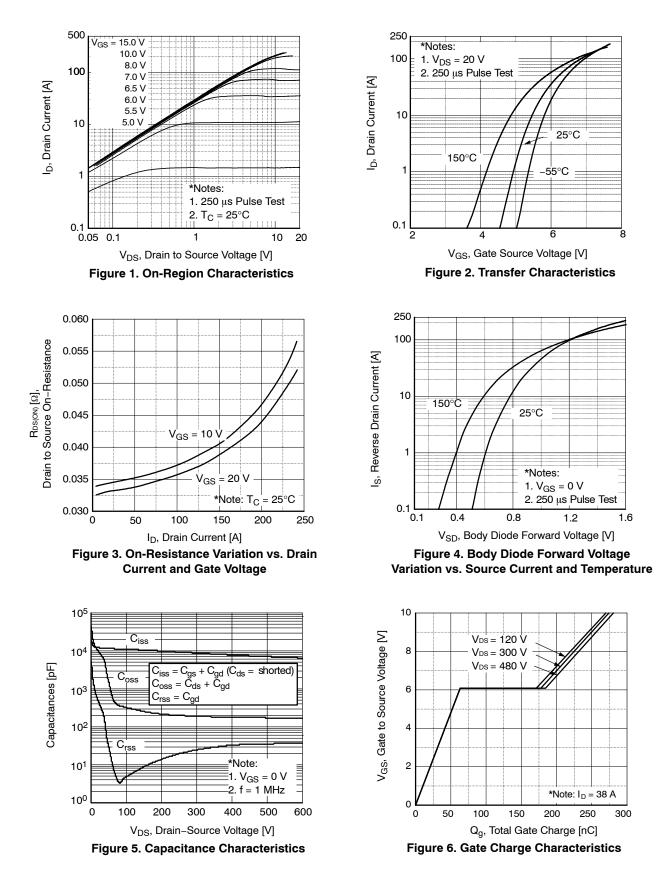
Part Number	Top Marking	Package	Packing Method	Reel Size	Tape Width	Quantity
FCH041N60F	FCH041N60F	TO-247	Tube	N/A	N/A	30 Units

#### **ELECTRICAL CHARACTERISTICS** ( $T_C = 25^{\circ}C$ unless otherwise noted)

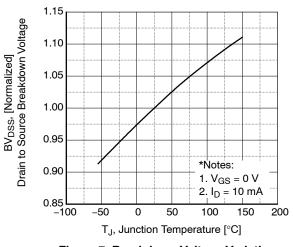
Symbol	Parameter	Test Conditions	Min	Тур	Max	Unit
OFF CHARACT	ERISTICS	-				
BV <sub>DSS</sub>	Drain to Source Breakdown Voltage	$V_{GS} = 0 \text{ V}, \text{ I}_{D} = 10 \text{ mA}, \text{ T}_{J} = 25^{\circ}\text{C}$	600	-	-	V
		$V_{GS}$ = 0 V, $I_{D}$ = 10 mA, $T_{J}$ = 150°C	650	-	-	
$\Delta \text{BV}_{\text{DSS}}\!/\!\Delta\text{T}_{\text{J}}$	Breakdown Voltage Temperature Coefficient	$I_D = 10$ mA, Referenced to $25^{\circ}C$	-	0.67	-	V/°C
I <sub>DSS</sub>	Zero Gate Voltage Drain Current	$V_{DS} = 600 \text{ V}, V_{GS} = 0 \text{ V}$	-	-	10	μA
		$V_{DS}$ = 480 V, $T_{C}$ = 125°C	-	267	-	1
I <sub>GSS</sub>	Gate to Body Leakage Current	$V_{GS}$ = ±20 V, $V_{DS}$ = 0 V	-	-	±100	nA
ON CHARACTE	RISTICS					
V <sub>GS(th)</sub>	Gate Threshold Voltage	$V_{GS} = V_{DS}, I_D = 250 \ \mu A$	3	-	5	V
R <sub>DS(on)</sub>	Static Drain to Source On Resistance	V <sub>GS</sub> = 10 V, I <sub>D</sub> = 38 A	-	36	41	mΩ
9 <sub>FS</sub>	Forward Transconductance	V <sub>DS</sub> = 20 V, I <sub>D</sub> = 38 A	-	64.5	-	S
DYNAMIC CHA	RACTERISTICS	•				
C <sub>iss</sub>	Input Capacitance	$V_{DS}$ = 100 V, $V_{GS}$ = 0 V, f = 1 MHz	-	10800	14365	pF
C <sub>oss</sub>	Output Capacitance		-	324	430	pF
C <sub>rss</sub>	Reverse Transfer Capacitance	-	-	4.5	_	pF
C <sub>oss</sub>	Output Capacitance	$V_{DS}$ = 380 V, $V_{GS}$ = 0 V, f = 1 MHz	-	185	-	pF
C <sub>oss(eff.)</sub>	Effective Output Capacitance	$V_{DS}$ = 0 V to 480 V, $V_{GS}$ = 0 V	-	748	-	pF
Q <sub>g(tot)</sub>	Total Gate Charge at 10 V	V <sub>DS</sub> = 380 V, I <sub>D</sub> = 38 A, V <sub>GS</sub> = 10 V (Note 4)	-	277	360	nC
Q <sub>gs</sub>	Gate to Source Gate Charge		-	65.3	-	nC
Q <sub>gd</sub>	Gate to Drain "Miller" Charge		-	116	-	nC
ESR	Equivalent Series Resistance	f = 1 MHz	-	1.0	-	Ω
WITCHING CH	IARACTERISTICS	•				
t <sub>d(on)</sub>	Turn-On Delay Time	V <sub>DD</sub> = 380 V, I <sub>D</sub> = 38 A,	-	63	136	ns
t <sub>r</sub>	Turn-On Rise Time	V <sub>GS</sub> = 10 V, R <sub>G</sub> = 4.7 Ω (Note 4)	-	66	142	ns
t <sub>d(off)</sub>	Turn-Off Delay Time		-	244	498	ns
t <sub>f</sub>	Turn-Off Fall Time		-	53	116	ns
SOURCE-DRAI	N DIODE CHARACTERISTICS		•	1		
ا <sub>S</sub>	Maximum Continuous Source to Drain Diode Forward Current		-	-	77	А
I <sub>SM</sub>	Maximum Pulsed Drain to Source Diode Forward Current			-	231	А
V <sub>SD</sub>	Drain to Source Diode Forward Voltage	V <sub>GS</sub> = 0 V, I <sub>SD</sub> = 38 A	-	-	1.2	V
t <sub>rr</sub>	Reverse Recovery Time	V <sub>GS</sub> = 0 V, I <sub>SD</sub> = 38 A,	-	214	-	ns
Q <sub>rr</sub>	Reverse Recovery Charge	dI <sub>F</sub> /dt = 100 A/μs	-	1.79	-	μC

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.
4. Essentially independent of operating temperature typical characteristics.

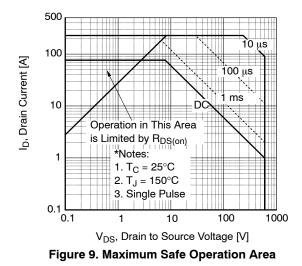
#### **TYPICAL PERFORMANCE CHARACTERISTICS**



#### TYPICAL PERFORMANCE CHARACTERISTICS (continued)







V<sub>DS</sub>, Drain to Source Voltage [V]

Figure 11. E<sub>OSS</sub> vs. Drain to Source Voltage

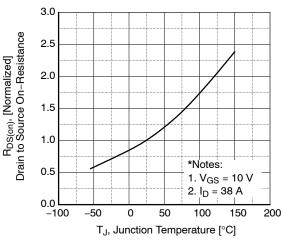
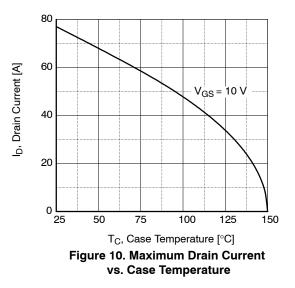


Figure 8. On-Resistance Variation vs. Temperature



## TYPICAL PERFORMANCE CHARACTERISTICS (continued)

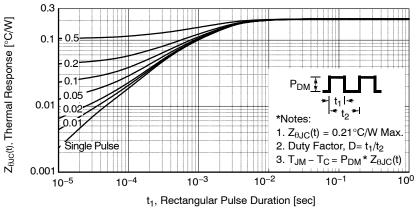
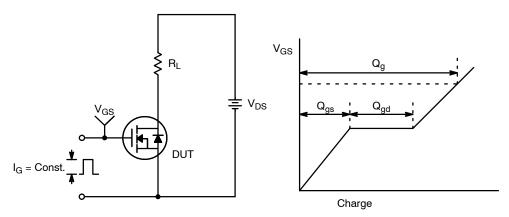


Figure 12. Transient Thermal Response Curve





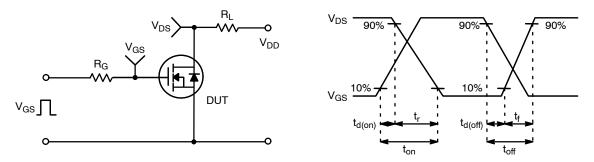


Figure 14. Resistive Switching Test Circuit & Waveforms

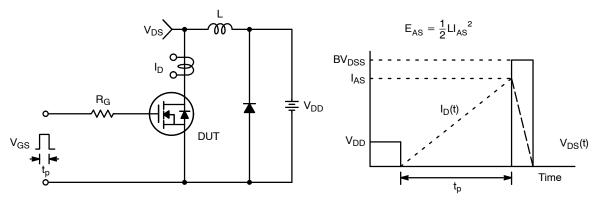


Figure 15. Unclamped Inductive Switching Test Circuit & Waveforms

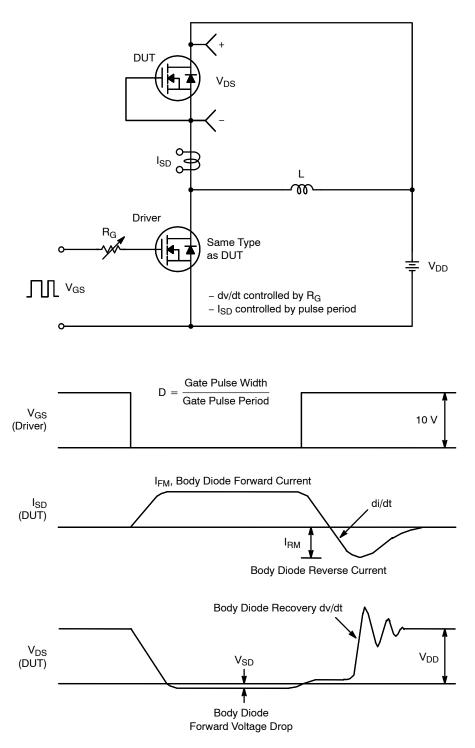


Figure 16. Peak Diode Recovery dv/dt Test Circuit & Waveforms

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